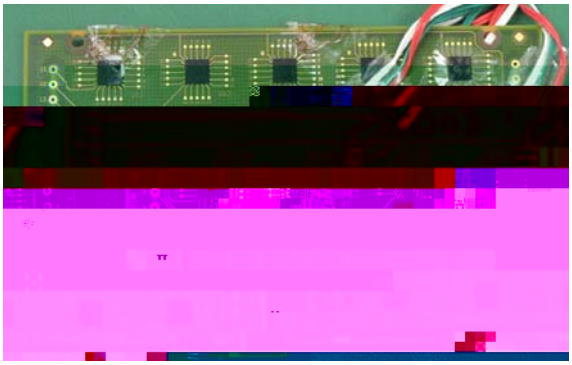
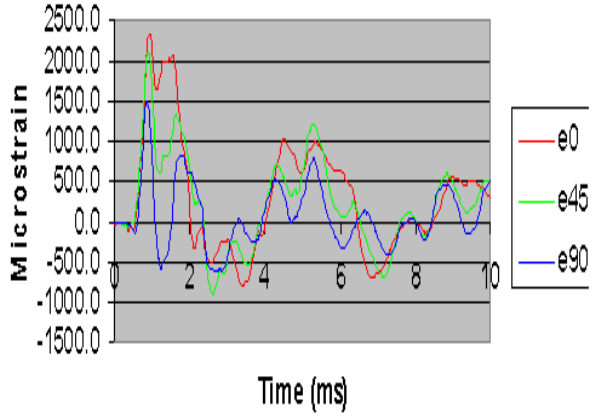
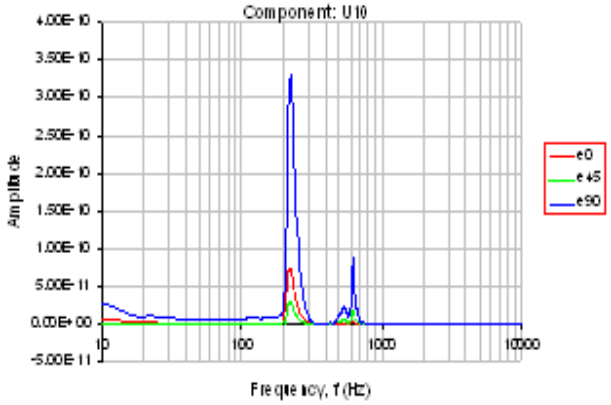
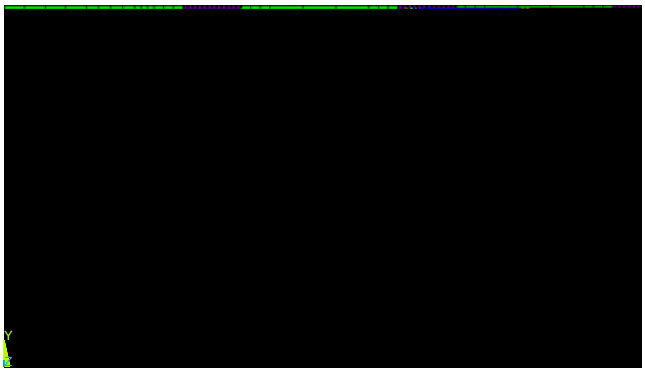
Shock Performance Study of Solder Joints in Wafer Level Packages

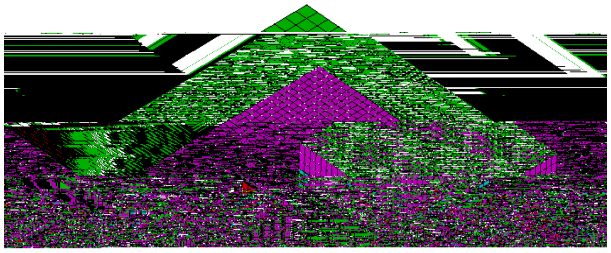
2. Experimental Setup [6]



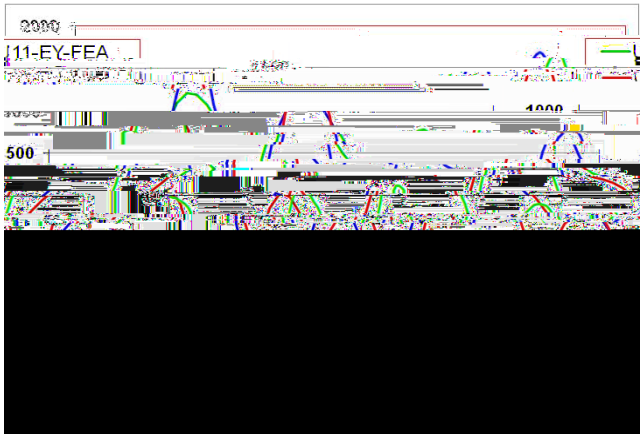

2500.0
2000.0
1500.0
1000.0
500.0
0.0
-500.0
-1000.0
-1500.0
Microstrain
0
2
4
6
8
10
Time (ms)
e0
e45
e90

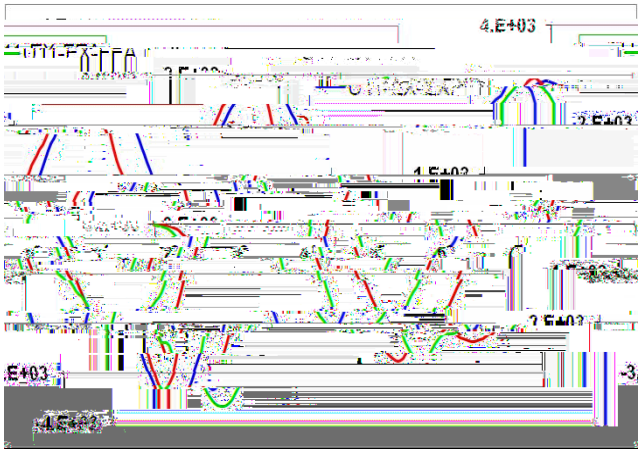

Component: U10
4.00E-10
3.50E-10
3.00E-10
2.50E-10
2.00E-10
1.50E-10
1.00E-10
5.00E-11
0.00E+00
-5.00E-11
Amplitude
10
100
1000
10000
Frequency, f (Hz)
e0
e45
e90


Y

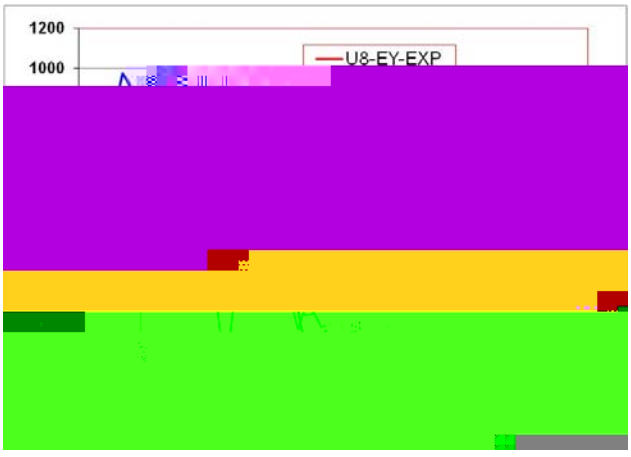


X

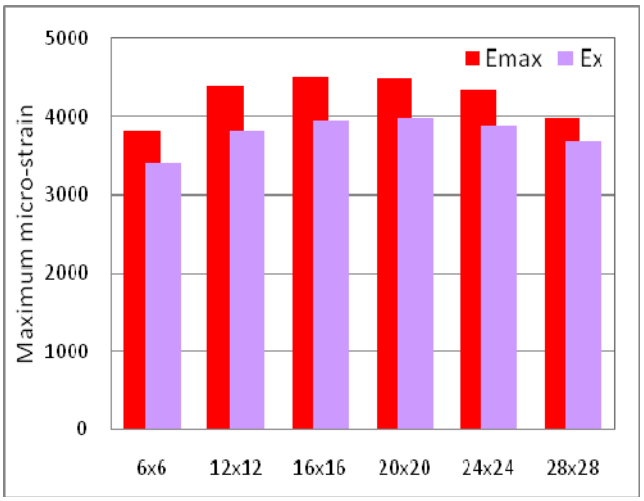


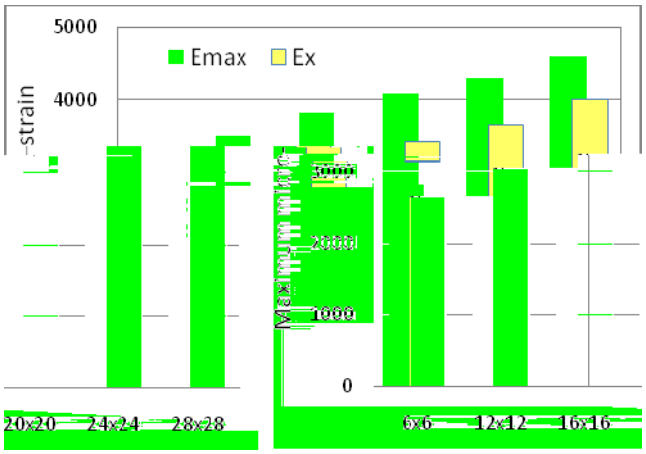


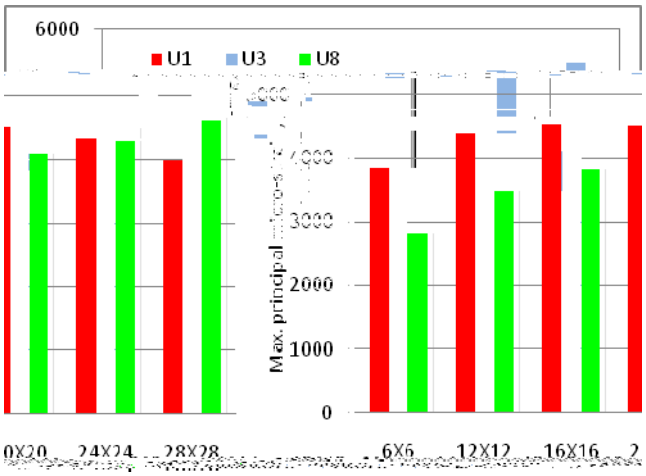
5 Board Strains An8 t(Bsig,s4(r)2(ig37.0536 37 t5 Boar

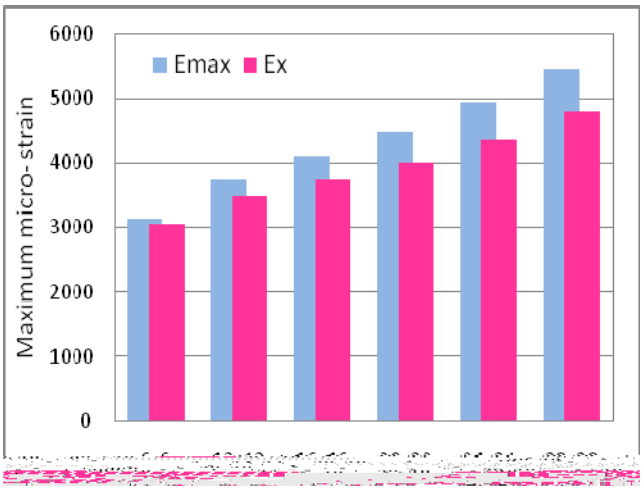


5.2 Effect of Array Size

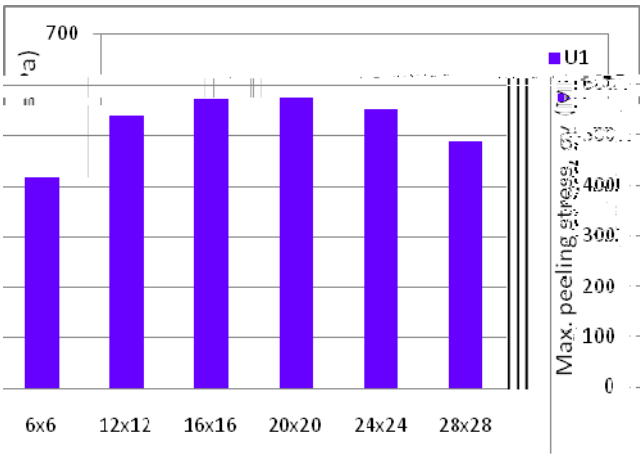








6. Strain Comparison between Global and Local Models


700
U1
400
300
200
100
0
6x6
12x12
16x16
20x20
24x24
28x28

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